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Joel A. Kubby
Graham T. Reed
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Contents

vii	Conference Committee
ix	Introduction

SESSION 1 WAVEGUIDES

- 7220 02 **Polarization diversity circuit based on a double-core structure consisting of silicon photonic wire and silicon-oxinitride waveguide (Invited Paper)** [7220-01]
K. Yamada, H. Fukuda, T. Tsuchizawa, T. Watanabe, H. Shinojima, H. Nishi, S. Itabashi, NTT Corp. (Japan)
- 7220 03 **The design of signal processing devices employing SOI MMI couplers** [7220-02]
L. W. Cahill, T. T. Le, La Trobe Univ. (Australia)
- 7220 04 **Optical characteristics of V-groove waveguide structures** [7220-03]
P. Müllner, R. Hainberger, Austrian Research Ctrs. GmbH (Austria)
- 7220 05 **Sub-wavelength grating gradient index mode transformers in high index contrast slab waveguides** [7220-04]
P. J. Bock, Univ. of Ottawa (Canada) and National Research Council Canada (Canada);
P. Cheben, J. H. Schmid, D.-X. Xu, S. Janz, National Research Council Canada (Canada);
T. J. Hall, Univ. of Ottawa (Canada)
- 7220 06 **Free carrier lifetime modification in silicon** [7220-05]
N. M. Wright, D. J. Thomson, K. L. Litvinenko, W. R. Headley, A. J. Smith, Univ. of Surrey (United Kingdom); A. P. Knights, McMaster Univ. (Canada); J. H. B. Deane, F. Y. Gardes, G. Z. Mashanovich, R. Gwilliam, G. T. Reed, Univ. of Surrey (United Kingdom)

SESSION 2 MODULATORS

- 7220 08 **Hybrid silicon modulators (Invited Paper)** [7220-07]
H.-W. Chen, Y. Kuo, J. E. Bowers, Univ. of California, Santa Barbara (United States)

SESSION 3 INTEGRATION

- 7220 0A **Silicon photonics developments in Europe (Invited Paper)** [7220-09]
J. M. Fedeli, CEA-DRT, LETI (France); J. Marti, Univ. Politcnica de Valencia (Spain); D. Van Thourhout, Ghent Univ. (Belgium); G. Reed, Univ. of Surrey (United Kingdom); T. White, Univ. of St. Andrews (United Kingdom)

- 7220 0B **High speed analog-to-digital conversion with silicon photonics (Invited Paper)** [7220-10]
C. W. Holzwarth, R. Amatya, M. Araghchini, J. Birge, H. Byun, J. Chen, M. Dahlem,
N. A. DiLello, F. Gan, J. L. Hoyt, E. P. Ippen, F. X. Kärtner, A. Khilo, J. Kim, M. Kim,
A. R. Motamedi, J. S. Orcutt, M. Park, M. Perrott, M. A. Popović, R. J. Ram, H. I. Smith,
G. R. Zhou, Massachusetts Institute of Technology (United States); S. J. Spector,
T. M. Lyszczarz, M. W. Geis, D. M. Lennon, J. U. Yoon, M. E. Grein, R. T. Schulein, MIT Lincoln
Lab. (United States); S. Frolov, A. Hanjani, J. Shmulovich, CyOptics (United States)
- 7220 0C **Universal PIN photodiodes in a 0.35µm BiCMOS mixed-signal ASIC technology** [7220-11]
A. Marchlewski, Vienna Univ. of Technology (Austria); G. Meinhardt, I. Jonak-Auer, V. Vescoli,
E. Wachmann, austriamicrosystems AG (Austria); K. Schneider-Hornstein, H. Zimmermann,
Vienna Univ. of Technology (Austria)
- 7220 0D **Compact silicon-based wavelength-selective photonic integrated devices and the
applications (Invited Paper)** [7220-12]
D. Dai, S. He, Zhejiang Univ. (China)

SESSION 4 DETECTORS

- 7220 0F **Ge-on-silicon vertical PIN photodetectors** [7220-14]
J. Osmond, L. Vivien, Institut d'Electronique Fondamentale, Univ. Paris-Sud, CNRS (France);
J. Fédéli, CEA-DRT, LETI (France); D. Marris-Morini, P. Crozat, Institut d'Electronique
Fondamentale, Univ. Paris-Sud, CNRS (France); J.-F. Damlencourt, CEA-DRT, LETI (France);
E. Cassan, J. Mangeney, Institut d'Electronique Fondamentale, Univ. Paris-Sud, CNRS
(France); Y. Lecunff, CEA-DRT, LETI (France); S. Laval, Institut d'Electronique Fondamentale,
Univ. Paris-Sud, CNRS (France)
- 7220 0H **Solid state photomultipliers and Geiger photodiodes with integrated readout and signal
processing** [7220-16]
C. J. Stapels, E. B. Johnson, S. Mukhopadhyay, P. S. Lindsay, E. C. Chapman, J. F. Christian,
RMD, Inc. (United States)

SESSION 5 LAB ON A CHIP I

- 7220 0K **Reconfigurable optofluidic silicon-based photonic crystal components** [7220-19]
C. Karnutsch, U. Bog, C. L. C. Smith, S. Tomljenovic-Hanic, C. Grillet, C. Monat, The Univ. of
Sydney (Australia); L. O'Faolain, T. White, T. F. Krauss, Univ. of St. Andrews (United Kingdom);
R. McPhedran, B. J. Eggleton, The Univ. of Sydney (Australia)
- 7220 0L **Biosensing microsystem platforms based on the integration of Si Mach-Zehnder
interferometer, microfluidics and grating couplers (Invited Paper)** [7220-20]
L. M. Lechuga, Research Ctr. on Nanoscience and Nanotechnology (CIN2) (Spain);
K. Zinoviev, Instituto de Microelectrónica de Barcelona (Spain); L. Fernández, J. Elizalde,
IKERLAN S. Coop (Spain); O. E. Hidalgo, Research Ctr. on Nanoscience and
Nanotechnology (CIN2) (Spain); C. Dominguez, Instituto de Microelectrónica de Barcelona
(Spain)

- 7220 ON **A robust silicon photonic platform for multiparameter biological analysis (Invited Paper)** [7220-22]
R. C. Bailey, A. L. Washburn, A. J. Qavi, Univ. of Illinois at Urbana-Champaign (United States);
M. Iqbal, M. Gleeson, F. Tybor, L. C. Gunn, Genalyte, Inc. (United States)

SESSION 6 LAB ON A CHIP II

- 7220 OO **Biosensors in silicon on insulator (Invited Paper)** [7220-23]
P. Bienstman, K. De Vos, T. Claes, P. Debackere, R. Baets, J. Girones, E. Schacht, Ghent Univ. (Belgium)
- 7220 OP **Micro-nano photonic biosensors scalable at the wafer level (Invited Paper)** [7220-24]
M. Holgado, R. Casquel, M.-F. Lagunas, Univ. Politécnica de Madrid (Spain)

SESSION 7 SILICON PHOTONICS

- 7220 OS **Self-assembled InGaAs/GaAs quantum dot microtube coherent light sources on GaAs and silicon (Invited Paper)** [7220-27]
Z. Mi, S. Vicknesh, F. Li, McGill Univ. (Canada); P. Bhattacharya, Univ. of Michigan (United States)

SESSION 8 RESONATORS AND INTERCONNECTS

- 7220 OU **Physical layer design of nanoscale silicon photonic interconnection networks (Invited Paper)** [7220-29]
K. Bergman, Columbia Univ. (United States)
- 7220 OV **The integration of silicon photonics and VLSI electronics for computing systems intra-connect (Invited Paper)** [7220-30]
A. V. Krishnamoorthy, R. Ho, X. Zheng, H. Schwetman, J. Lexau, P. Koka, G. Li, I. Shubin, J. E. Cunningham, Sun Microsystems, Inc. (United States)
- 7220 OW **Complete optical isolation created by indirect interband photonic transitions** [7220-31]
Z. Yu, S. Fan, Stanford Univ. (United States)
- 7220 OY **Identifying resonance frequency deviations for high order nano-wire ring resonator filters based on a coupling strength variation** [7220-33]
S. Park, Electronics and Telecommunications Research Institute (Korea, Republic of); K.-J. Kim, Electronics and Telecommunications Research Institute (Korea, Republic of) and Korea Advanced Institute of Science and Technology (Korea, Republic of); D.-J. Kim, G. Kim, Electronics and Telecommunications Research Institute (Korea, Republic of)

SESSION 9 RESONATORS AND WAVEGUIDE DEVICES

- 7220 11 **Fabrication and tailoring of silicon photonic devices via focused ion beam** [7220-36]
S. Howe, W. R. Headley, D. C. Cox, G. Z. Mashanovich, D. J. Thomson, G. T. Reed, Univ. of Surrey (United Kingdom)

POSTER SESSION

- 7220 14 **On-chip silicon photonic wavelength control of laser source** [7220-40]
X. Wang, T. Liu, Florida International Univ. (United States); V. R. Almeida, Instituto de Estudos Avançados (Brazil) and Instituto Tecnológico de Aeronáutica (Brazil); R. R. Panepucci, Florida International Univ. (United States)

Author Index

Conference Committee

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1 Waveguides

Graham T. Reed, University of Surrey (United Kingdom)

2 Modulators

Philippe M. Fauchet, University of Rochester (United States)

3 Integration

Graham T. Reed, University of Surrey (United Kingdom)

- 4 Detectors
Paul E. Jessop, McMaster University (Canada)
- 5 Lab on a Chip I
Laurence W. Cahill, La Trobe University (Australia)
- 6 Lab on a Chip II
Laura M. Lechuga, Research Center on Nanoscience and Nanotechnology (CIN2) (Spain)
- 7 Silicon Photonics
Mario J. Paniccia, Intel Corporation (United States)
- 8 Resonators and Interconnects
Graham T. Reed, University of Surrey (United Kingdom)
- 9 Resonators and Waveguide Devices
Joel A. Kubby, University of California, Santa Cruz (United States)
- 10 Emitters
Joel A. Kubby, University of California, Santa Cruz (United States)

Introduction

Silicon has a legendary history as the material of choice for microelectronic integration, but has not been the material of choice for optoelectronic integration. That is now beginning to change with the introduction of monolithic and hybrid silicon photonics. Silicon photonic devices have been demonstrated with the capability to emit, modulate, guide and detect light and can be combined with microelectronics to form electronic and photonic integrated circuits. Silicon photonic devices such as high-speed (40 GSa/s) analog to digital converters are now being fabricated in commercial CMOS foundries, enabling these devices to leverage the \$500 billion fabrication infrastructure for integrated circuits. The previous barrier of silicon's indirect bandgap has been overcome through the integration of germanium and III-V materials to form novel in-plane silicon lasers and high-speed (16 GHz) modulators. The cascaded Raman effect and nano-engineering of crystalline silicon and silicon-rich nitride films have also been used to obtain light from silicon and an electrically pumped silicon laser is on the horizon.

The decrease in waveguide bend radius made possible in silicon due to its high-index contrast, together with increased levels of optical and microelectronic integration, may lead to a new formulation of Moore's Law for silicon photonics. We are now seeing the convergence of communications and computing directly on-chip with the advent of optical interconnects, driven by the need for smaller and less expensive components that can leverage the infrastructure for CMOS manufacturing. In addition to on-chip communications and signal processing, silicon photonics is also being used to form laboratories on a chip with integrated micro-fluidics for low-cost, label-free biosensing. The past year has been an exciting time for silicon photonics! We hope you will enjoy the papers detailing these advancements that are included in this conference proceeding.

Joel A. Kubby
Graham T. Reed